

# S1A THRU S1M

### 1.0 AMP. Surface Mount Rectifiers



Voltage Range 50 to 1000 Volts Current 1.0 Ampere

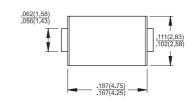
#### **Features**

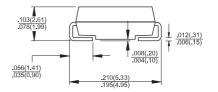
- ♦ For surface mounted application
- Glass passivated junction chip.
- Low forward voltage drop
- High current capability
- ♦ Easy pick and place
- High surge current capability
- Plastic material used carries Underwriters Laboratory Classification 94V-O
- High temperature soldering:
   260°C / 10 seconds at terminals

### **Mechanical Data**

- ♦ Case: Molded plastic
  ♦ Tarminals: Salder plates
- ♦ Terminals: Solder plated
   ♦ Polarity: Indicated by cathode band
- Packaging: 12mm tape per EIA STD RS-481
- ♦ Weight: 0.064 gram

## SMA/DO-214AC





Dimensions in inches and (millimeters)

# Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @ $T_L$ =110 $^{\circ}$ C	I <sub>(AV)</sub>	1.0							Α
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I <sub>FSM</sub>	30							Α
Maximum Instantaneous Forward Voltage @ 1.0A	$V_{F}$	1.1							V
Maximum DC Reverse Current @ $T_A = 25^{\circ}$ C at Rated DC Blocking Voltage @ $T_A = 125^{\circ}$ C	I <sub>R</sub>	5 50							uA uA
Typical Thermal Resistance (Note 3)	RθJL	27					3	80	°C/W
	RθJA			75			8	5	
Maximum Reverse Recovery Time ( Note 1 )	Trr	1.8							uS
Typical Junction Capacitance (Note 2)	Cj	12							pF
Operating Temperature Range	TJ	-55 to +150							$^{\circ}\mathbb{C}$
Storage Temperature Range	TSTG	-55 to +150							$^{\circ}\!\mathbb{C}$

Notes: 1. Reverse Recovery Test Conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

- 2. Measured at 1 MHz and Applied V<sub>R</sub>=4.0 Volts
- 3.Measured on P.C. Board with 0.2 x 0.2" (5.0 x 5.0mm) Copper Pad Areas.



#### RATINGS AND CHARACTERISTIC CURVES (SIA THRU SIM)

FIG.1- MAXIMUM FORWARD CURRENT DERATING 1.2 € 1.0 AVERAGE FORWARD CURRENT. .20IN<sup>2</sup> (5.0mm<sup>2</sup>) x 0.5mil inches(0.013mm) Thick Copper Pad Areas 0.8 0.6 0.4 0.2 0 0 20 40 60 80 100 120 140 LEAD TEMPERATURE. (°C)

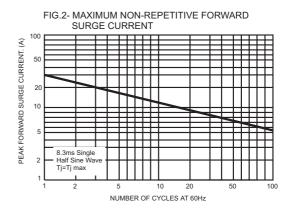


FIG.3- TYPICAL FORWARD CHARACTERISTICS

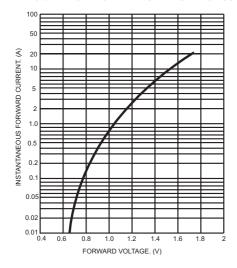


FIG.4- TYPICAL REVERSE CHARACTERISTICS

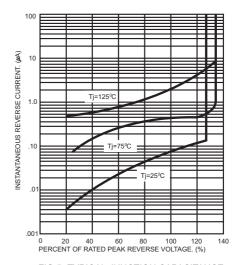


FIG.5- TYPICAL JUNCTION CAPACITANCE

